



# Minutes of U-1 Committee

**Tuesday 07 October, 2003**  
**San Antonio Marriott Rivercenter**  
**San Antonio, TX**

Attendees:

<b>NAME</b>	<b>COMPANY</b>
Susan Barkal	Kemet Electronics
Joe Biernacki	SEI Electronics
Michael C. Cannon	TDK Corporation
Terry D. Charles	Panasonic
Yumi Chiong Aihara	KRFM America Inc.
Ted Coler	Vishay
Dennis Cross	DSCC
Phil Diglio	EPCOS Inc
Dan Giblin	Cooper Bussmann
Bill Gisseler	TDK Corporation of America
Michael Griffith	KOA Speer Electronics
Frank B. Hayward	American Technical Ceramics
Matt Joiner	Cooper Bussmann
Kunifumi Komiya	KRFM America Inc.
Masanori Kujiraoka	Taiyo Yuden (USA)
Patrick Kyne	DSCC
Carl Lindquist	San-O Industrial
Laird L. Macomber	Cornell Dublier
Maher Mahmud	IBM Corp
Karun Malhotra	Murata Electronics, NA
Len Metzger	Panasonic Industrial Co.
Ed Mikoski	EIA/ECA
Randy Pinkelman	Vishay Dale Resistors
Chris Reynolds	AVX
Dave Ritchey	Yageo/Phycomp
Dave Toomey	Vishay
Harvey Waltersdorf	ECA
Michael Whitney	IBM

The meeting was called-to-order by Acting Chairman Edward Mikoski at 8:00am.

## 1.0 Membership Attendance and Introductions

1.1 There was a round of self introductions.

### 1.2 Membership and Attendance

Attendance was taken, and it was determined that a quorum was present.

<u>Member Organizations</u>	<u>Present at this meeting</u>	<u>Present at previous meeting?</u>	<u>Present at meeting prior to previous?</u>	
AEM, Inc	No	Y	Y	
American Technical Ceramics	Y	Y	Y	
AVX	Y	Y	No	
Cooper Bussmann	Y	Y	Y	
Cornell Dublier	Y	Y	Y	
CTS	N	Y	N	
DSCC	Y	N	Y	
EPCOS Inc	Y	N	N	
IBM Corp	Y	Y	Y	
Kemet Electronics	Y	Y	Y	
KOA Speer Electronics	Y	Y	Y	
KRFM America, Inc	Y	NA	NA	
Littelfuse*	N	N	N	
Lucent Technologies*	N	N	N	
Maxwell Tehcnologies	N	NA	NA	
Mini-Systems Inc	N	Y	N	
Murata Electronics	Y	Y	Y	
Panasonic	Y	Y	Y	
San-O Industrial	Y	Y	N	
SEI Electronics	Y	N	N	
Taiyo Yuden	Y	Y	N	
TDK Corporation	Y	Y	N	
Vishay	Y	Y	Y	
Visteon	N	Y	N	
Yageo/Phycomp	Y	Y	Y	

\* Not counted in determination of quorum due to non-attendance

<u>Other Organizations Present</u>
EIA/ECA

## 2.0 Approval of Agenda

Agenda was unanimously approved.

### **3.0 Approval of U-1 April 15, 2003 Minutes**

Minutes were unanimously approved.

### **4.0 Correspondence**

The Chair had contacted the Chair of GEIA Committee G-11 for a report. The draft minutes of the recent G-11 Committee were forwarded to cover highlights with the U-1 committee. It was felt by the group that it would be a good idea to regularly review the activities and determine where joint activities might be beneficial.

### **5.0 Sub-Committee & Working Group Reports**

Each of the Sub-Committees and Working Groups gave a brief summary of their activities taking place during this week. Details of the subsequent activities can be found in the individual minutes of the Sub-Committee Reports.

### **6.0 Environmental Update – EIA**

The EIA through its Environmental Issues Council is very active in environmental legislation and regulatory issues. Member companies of EIA are eligible to participate on the Council. The EIC has a world-wide tracking database regarding environmental regulatory developments. EIA has also been working the last several years on a Materials Declaration Guide for the Electronics Industry. The activity has been jointly coordinated with JGPSSI through JEITA in Japan, and EICTA in Europe. A formal committee has been established to evolve the draft work into a formalized standard for the industry. Interested parties should contact Ed Mikoski.

### **7.0 Other event announcements**

ECA is involved in multiple conferences and symposia. Visit the ECA website for more details. Also it was announced that the ECA would be conducting a marketing session during the upcoming International Wire and Cable Symposium to be Held in Philadelphia in November. This should be of significant interest to the cable manufacturers and materials suppliers.

### **8.0 Old Business**

#### **8.1 ECA Website Update.**

The ECA website continues to evolve into higher levels of value to members and industry. A “Marketplace” where Market Statistics Reports, Industry Documents and Publications of interest, conference proceedings, etc., will be available shortly. Member companies are eligible for a discount.

### **9.0 NEW BUSINESS**

## **9.1 Lead Free - Industry Update**

These types of issues will be discussed and addressed in the Soldering Technology Committee meeting this week.

## **9.2 Presentation - Technical Paper**

### **9.2.1 New member; KRFM presentation.**

Dr. Kunifumi Komiya, President of KRFM America Inc. a new member to the ECA delivered a presentation covering the Product Lines they have developed and the associated technology. KRFM AMERICA, Inc. products include Decoupling filter products and Hybrid ICs. KRFM Japan is an RF electronic technology firm established in 1998 in Yokohama Japan, specializing in developing Microwave components, Wideband decoupling filters for high speed applications such as Optical Fiber(10GbE) Modules, Storage Servers and Wireless Telecommunication Equipments. The products eliminate the harmonics noise, minimizes electromagnetic emissions and interferences. Each application utilizes this product line to develop end-user products that comply with FCC (Federal Communications Commission) and CE emission regulations.

### **9.2.2 Mike Whitney, IBM on B-to-B processes for Component Technical Data Exchange**

Mike Whitney of IBM delivered a comprehensive presentation on the subject. ABSTRACT - RosettaNet is a leading industry standard for business-to-business transactions that has been gaining wide acceptance in IBM and the connector industry. Most of the focus on implementing RosettaNet standards has targeted automating business processes. However, IBM is also streamlining processes that use technical data by implementing RosettaNet process 2A9, "Query Technical Product Information", with connector suppliers. This process supports the automation of technical data transfer between suppliers and IBM. When fully implemented, this process will save hundreds of hours of manual data entry per year at IBM and our suppliers, and it will alleviate many data integrity and quality problems in IBM, which better enables strategic and convergence processes. This paper describes the process by which the information can be exchanged, and documents the advantages observed by implementing the system. The technical data model and parts classification system used by RosettaNet is also reviewed and compared to the IBM model. Future plans for implementation of other RosettaNet technical processes, including processes for Part/Process Change Notification and End Of Life notification, are also discussed.

## **10.0 Next Meeting**

The next meeting will be held at the ECA Spring 2004 Engineering Summit to be held the week of 19-22 April, 2004 at Hilton Tampa Westshore, Tampa Bay, FL.

The ECA Fall 2004 Engineering Summit location is being planned for San Diego, CA

The ECA Spring 2005 Engineering Summit primary location site will be New Orleans, LA with a backup location of Denver, CO

### **11.0 Adjournment**

The meeting was adjourned at 12:00 pm.

This meeting was conducted in accordance with the EIA Legal Guidelines and the Manual of Organization and Procedures.

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Edward F. Mikoski, Jr.  
Acting Chairman

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Edward F. Mikoski, Jr.  
Acting Secretary